

Cond
A1
device is provided in the back surface portion 141. The opening portion 523 is covered with a cover (not shown) in regular use.

IN THE CLAIMS

Please cancel claims 1 and 2 without prejudice or disclaimer.

Please amend claims 3, 8, 9, 17 and 18 as follows:

A2
C1
3. (Amended) A circuit substrate unit for mounting a circuit element, which comprises:
a plurality of circuit substrates, each of which mounts a circuit element thereon; and
at least one heat sink member,
wherein at least one of said plurality of circuit substrates is stacked on one of the circuit substrates adjacent thereto with a space therebetween, and
said heat sink member is arranged in the space formed between said adjacent circuit substrates.
wherein said heat sink member has a plurality of protruding portions on at least one of plane facing one of the two circuit substrates which sandwich said heat sink member therebetween, and
a circuit element arranged on said plane which faces said heat sink member is mounted on the circuit substrate in a state where the circuit element contacts with at least one of said plurality of protruding portions.

A3
C1
8. (Amended) The circuit unit according to claim 3,

cond
ACI
wherein others of said plurality of protruding portions are arranged to make no contact with the circuit element mounted on the circuit substrate facing the protruding portions.

9. (Amended) The circuit substrate unit according to claim 3,

wherein said heat sink member has a radiation fin partially provided therein.

AA
17. (Amended) Electronic equipment comprising a circuit substrate unit having:

a first circuit substrate;

a second circuit substrate;

a heat sink member; and

an electronic shield member;

cl
wherein said first circuit substrate and said second circuit substrate sandwich said heat sink member and said electromagnetic shield member therebetween.

18. (Amended) Electronic equipment comprising the circuit substrate unit according to claim 17, said circuit substrate unit further comprising:

a circuit element on said first circuit substrate serving as a first heat source,

a circuit element on said first circuit substrate serving as a second heat source,

a radiation fin on a plane of said heat sink member facing the second circuit substrate,

a plurality of protruding portions on the plane of said heat sink member facing the second circuit substrate, and

a hood portion,